**Product data sheet** 

## 1. General description

Silicon Carbide Schottky diode in a TO263-2L (D2PAK) plastic package, designed for high frequency switched-mode power supplies.



### 2. Features and benefits

- · Highly stable switching performance
- High forward surge capability I<sub>FSM</sub>
- · Extremely fast reverse recovery time
- Superior in efficiency to Silicon Diode alternatives
- Reduced losses in associated MOSFET
- Reduced EMI
- · Reduced cooling requirements
- RoHS compliant
- High junction operating temperature capability (T<sub>i(max)</sub> = 175 °C)

## 3. Applications

- Power factor correction
- Telecom/Server SMPS
- UPS
- PV inverter
- PC Silverbox
- LED/OLED TV
- Motor Drives

### 4. Quick reference data

### Table 1. Quick reference data

Symbol	Parameter	Conditions	Notes		Values		Unit
Absolute maximum rating							
$V_{RRM}$	repetitive peak reverse 1200 voltage				V		
$I_{F(AV)}$	average forward current	$δ$ = 0.5 ; square-wave pulse; $T_{mb}$ ≤ 143 °C; Fig. 1; Fig. 2; Fig. 3		15		А	
$T_j$	junction temperature			-55 to 175			°C
Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
Static ch	aracteristics						
$V_{F}$	forward voltage	I <sub>F</sub> = 15 A; T <sub>j</sub> = 25 °C; <u>Fig. 5</u>		-	1.42	1.60	V
		I <sub>F</sub> = 15 A; T <sub>j</sub> = 150 °C; <u>Fig. 5</u>		-	1.90	2.30	V
		I <sub>F</sub> = 15 A; T <sub>j</sub> = 175 °C; <u>Fig. 5</u>		-	2.00	2.50	V
Dynamic	Dynamic characteristics						
Q <sub>r</sub>	recovered charge	$I_F = 15 \text{ A}$ ; $dI_F/dt = 500 \text{ A/}\mu\text{s}$ ; $V_R = 400 \text{ V}$ ; $T_j = 25 ^{\circ}\text{C}$ ; Fig. 7		-	36	-	nC

# 5. Pinning information

### **Table 2. Pinning information**

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode	mb	K 14 A
2	А	anode		K <del>   </del> A 001aaa020
mb	mb	mounting base; connected to cathode	1 2 TO-263 (D2PAK)	

# 6. Ordering information

### **Table 3. Ordering information**

Type number	Package name	Orderable part number	Packing method	Small packing guantity	Package version	Package issue date
WNSC2D151200BT2	TO263-2L	WNSC2D151200BT26J	Reel	800	TO263N-2L	14-Oct-2022

## 7. Marking

#### Table 4. Marking codes

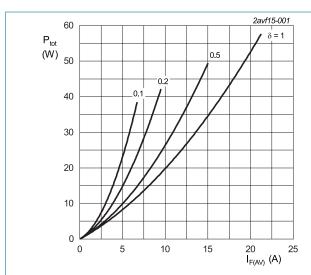
Type number	Marking codes
WNSC2D151200BT2	WNSC2D 151200BT2

## 8. Limiting values

#### **Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Notes	Values	Unit
$V_{RRM}$	repetitive peak reverse voltage			1200	V
$V_{\text{RWM}}$	crest working reverse voltage			1200	V
V <sub>R</sub>	reverse voltage	DC		1200	V
I <sub>F(AV)</sub>	average forward current	$\delta$ = 0.5; square-wave pulse; $T_{mb} \le 143$ °C; Fig. 1; Fig. 2; Fig. 3		15	А
I <sub>FRM</sub>	repetitive peak forward current	$\delta$ = 0.5; t <sub>p</sub> = 25 μs; T <sub>mb</sub> ≤ 143 °C; square-wave pulse		30	А
I <sub>FSM</sub>	non-repetitive peak	$t_p$ = 10 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse		140	А
	forward current	$t_p = 10 \mu s; T_{j(init)} = 25 °C; square-wave pulse$		900	Α
l²t	I <sup>2</sup> t for fusing	sine-wave pulse; $T_{j(init)} = 25 \text{ °C}$ ; $t_p = 10 \text{ ms}$		98	A <sup>2</sup> s
T <sub>stg</sub>	storage temperature			-55 to 175	°C
T <sub>j</sub>	junction temperature			-55 to 175	°C



$$\begin{split} I_{F(AV)} &= I_{F(RMS)} \times \sqrt{\delta} \\ V_{o} &= 1.321 \text{ V; } R_{s} = 0.0655 \text{ } \Omega \end{split}$$

Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values

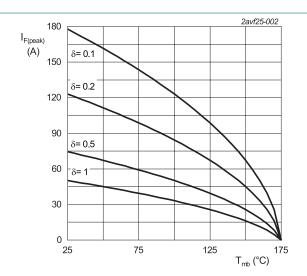
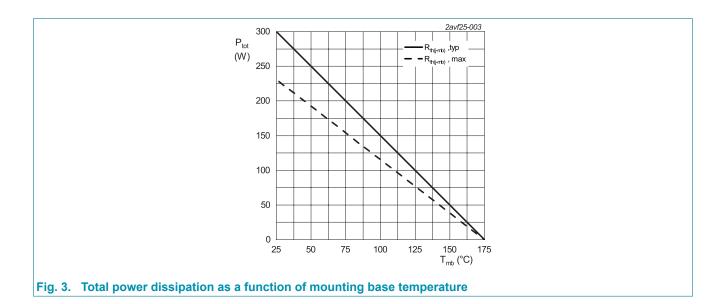


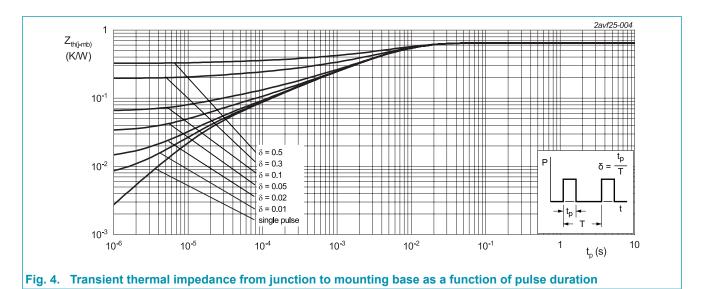
Fig. 2. Current derating as a function of mounting base temperature



## 9. Thermal characteristics

**Table 6. Thermal characteristics** 

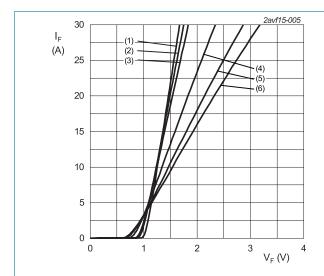
Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
R <sub>th(j-mb)</sub>	thermal resistance from junction to mounting base	Fig. 4		-	0.5	0.65	K/W
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient free air	in free air		-	40	-	K/W



## 10. Characteristics

Table 7. Characteristics

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Symbol	Parameter Conditions		Notes	Min	Тур	Max	Unit
Static cha	racteristics						
$V_{F}$	forward current	I <sub>F</sub> = 15 A; T <sub>j</sub> = 25 °C; <u>Fig. 5</u>		-	1.42	1.60	V
		I <sub>F</sub> = 15 A; T <sub>j</sub> = 150 °C; <u>Fig. 5</u>		-	1.90	2.30	V
		I <sub>F</sub> = 15 A; T <sub>j</sub> = 175 °C; <u>Fig. 5</u>		-	2.00	2.50	V
I <sub>R</sub>	reverse current	V <sub>R</sub> = 1200 V; T <sub>j</sub> = 25 °C; <u>Fig. 6</u>		-	1	75	μA
		V <sub>R</sub> = 1200 V; T <sub>j</sub> = 175 °C; <u>Fig. 6</u>		-	25	-	μA
Dynamic	characteristics						
$Q_r$	recovered charge	$I_F = 15 \text{ A}$ ; $V_R = 400 \text{ V}$ ; $dI_F/dt = 500 \text{ A/}\mu\text{s}$ ; $T_j = 25 \text{ °C}$ ; Fig. 7		-	36	-	nC
C <sub>d</sub>	diode capacitance	f = 1 MHz; V <sub>R</sub> = 1 V; T <sub>j</sub> = 25 °C		-	800	-	pF
		f = 1 MHz; V <sub>R</sub> = 400 V; T <sub>j</sub> = 25 °C		-	66	-	pF
		f = 1 MHz; V <sub>R</sub> = 800 V; T <sub>j</sub> = 25 °C		-	48	-	pF
E <sub>as</sub>	non-repetitive avalanche energy	$I_R = 4.7 \text{ A}$ ; L = 10 mH; $T_{j(init)} = 25  ^{\circ}\text{C}$		110	-	-	mJ



 $V_{o}$  = 1.321 V;  $R_{s}$  = 0.0655  $\Omega$ 

(1)  $T_i = -55$  °C; typical values

(2)  $T_i = 0$  °C; typical values

(3) T<sub>j</sub> = 25 °C; typical values

(4) T<sub>j</sub> = 100 °C; typical values

(5)  $T_j = 150$  °C; typical values

(6)  $T_i = 175 \,^{\circ}\text{C}$ ; typical values

Fig. 5. Forward current as a function of forward voltage; typical values

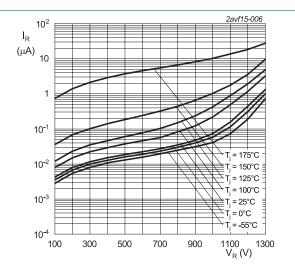


Fig. 6. Reverse leakage current as a function of reverse voltage; typical value

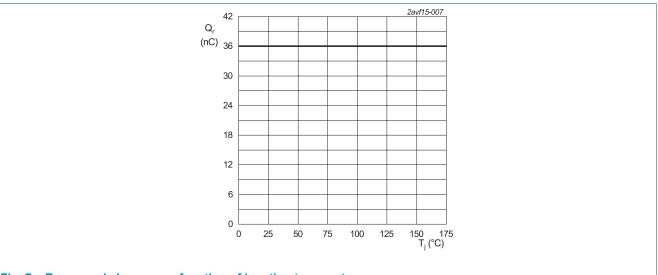
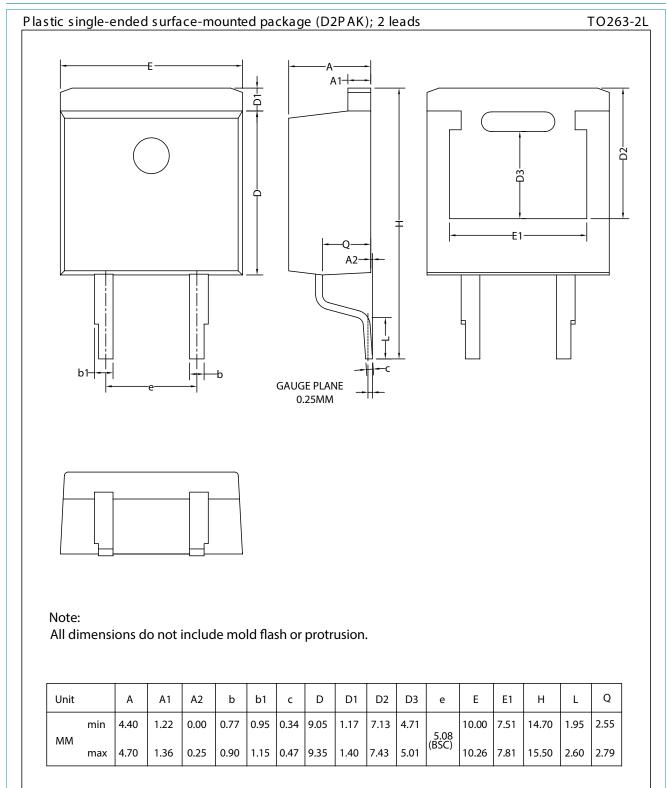


Fig. 7. Recovered charge as a function of junction temperature

# 11. Package outline



## 12. Legal information

#### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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